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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	19700
Total RAM Bits	434176
Number of I/O	360
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp20e-4fn484i

September 2012

Data Sheet

Features

- **Extensive Density and Package Options**
 - 1.5K to 32.8K LUT4s
 - 65 to 496 I/Os
 - Density migration supported
- **sysDSP™ Block (LatticeECP™ Versions)**
 - High performance multiply and accumulate
 - 4 to 8 blocks
 - 4 to 8 36x36 multipliers or
 - 16 to 32 18x18 multipliers or
 - 32 to 64 9x9 multipliers
- **Embedded and Distributed Memory**
 - 18 Kbits to 498 Kbits sysMEM™ Embedded Block RAM (EBR)
 - Up to 131 Kbits distributed RAM
 - Flexible memory resources:
 - Distributed and block memory
- **Flexible I/O Buffer**
 - Programmable sysI/O™ buffer supports wide range of interfaces:

- LVCMOS 3.3/2.5/1.8/1.5/1.2
- LVTTL
- SSSL 3/2 Class I, II, SSSL18 Class I
- HSTL 18 Class I, II, III, HSTL15 Class I, III
- PCI
- LVDS, Bus-LVDS, LVPECL, RSDS
- **Dedicated DDR Memory Support**
 - Implements interface up to DDR400 (200MHz)
- **sysCLOCK™ PLLs**
 - Up to four analog PLLs per device
 - Clock multiply, divide and phase shifting
- **System Level Support**
 - IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
 - SPI boot flash interface
 - 1.2V power supply
- **Low Cost FPGA**
 - Features optimized for mainstream applications
 - Low cost TQFP and PQFP packaging

Table 1-1. LatticeECP/EC Family Selection Guide

Device	LFEC1	LFEC3	LFEC6/ LFECP6	LFEC10/ LFECP10	LFEC15/ LFECP15	LFEC20/ LFECP20	LFEC33/ LFECP33
PFU/PFF Rows	12	16	24	32	40	44	64
PFU/PFF Columns	16	24	32	40	48	56	64
PFUs/PFFs	192	384	768	1280	1920	2464	4096
LUTs (K)	1.5	3.1	6.1	10.2	15.4	19.7	32.8
Distributed RAM (Kbits)	6	12	25	41	61	79	131
EBR SRAM (Kbits)	18	55	92	276	350	424	498
EBR SRAM Blocks	2	6	10	30	38	46	54
sysDSP Blocks ¹	—	—	4	5	6	7	8
18x18 Multipliers ¹	—	—	16	20	24	28	32
V _{CC} Voltage (V)	1.2	1.2	1.2	1.2	1.2	1.2	1.2
Number of PLLs	2	2	2	4	4	4	4
Packages and I/O Combinations:							
100-pin TQFP (14 x 14 mm)	67	67					
144-pin TQFP (20 x 20 mm)	97	97	97				
208-pin PQFP (28 x 28 mm)	112	145	147	147			
256-ball fpBGA (17 x 17 mm)		160	195	195	195		
484-ball fpBGA (23 x 23 mm)			224	288	352	360	360
672-ball fpBGA (27 x 27 mm)						400	496

1. LatticeECP devices only.

Introduction

The LatticeECP/EC family of FPGA devices is optimized to deliver mainstream FPGA features at low cost. For maximum performance and value, the LatticeECP™ (Economy Plus) FPGA concept combines an efficient FPGA fabric with high-speed dedicated functions. Lattice's first family to implement this approach is the LatticeECP-DSP™ (Economy Plus DSP) family, providing dedicated high-performance DSP blocks on-chip. The LatticeEC™ (Economy) family supports all the general purpose features of LatticeECP devices without dedicated function blocks to achieve lower cost solutions.

The LatticeECP/EC FPGA fabric, which was designed from the outset with low cost in mind, contains all the critical FPGA elements: LUT-based logic, distributed and embedded memory, PLLs and support for mainstream I/Os. Dedicated DDR memory interface logic is also included to support this memory that is becoming increasingly prevalent in cost-sensitive applications.

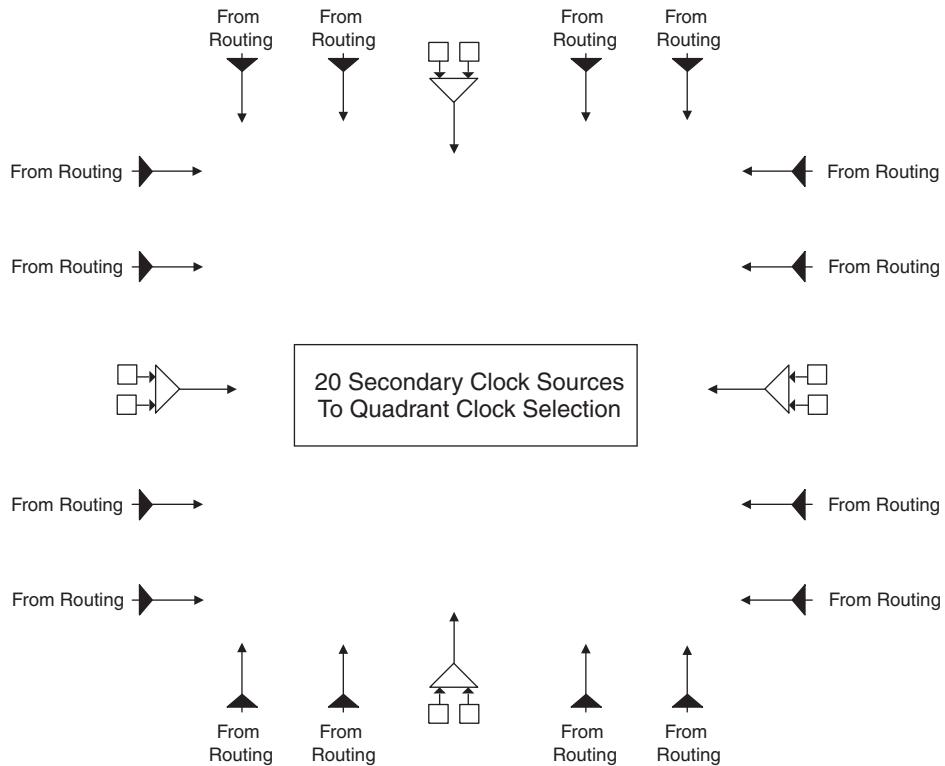
The ispLEVER® design tool suite from Lattice allows large complex designs to be efficiently implemented using the LatticeECP/EC FPGA family. Synthesis library support for LatticeECP/EC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeECP/EC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeECP/EC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Secondary Clock Sources

LatticeECP/EC devices have four secondary clock resources per quadrant. The secondary clock branches are tapped at every PFU. These secondary clock networks can also be used for controls and high fanout data. These secondary clocks are derived from four clock input pads and 16 routing signals as shown in Figure 2-7.

Figure 2-7. Secondary Clock Sources



Clock Routing

The clock routing structure in LatticeECP/EC devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXes located in each quadrant. Figure 2-8 shows this clock routing. The four secondary clocks are generated from MUXes located in each quadrant as shown in Figure 2-9. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-10.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeECP/EC family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysI/O Buffer Banks

LatticeECP/EC devices have eight sysI/O buffer banks; each is capable of supporting multiple I/O standards. Each sysI/O bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-34 shows the eight banks and their associated supplies.

In the LatticeECP/EC devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using V_{CCIO} . LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold input independent of V_{CCIO} . In addition to the bank V_{CCIO} supplies, the LatticeECP/EC devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeECP/EC devices, some dedicated I/O pins in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I _{CC}	Core Power Supply Current	LFEC1	6	mA
		LFEC3	10	mA
		LFECP6/LFEC6	15	mA
		LFECP10/LFEC10	25	mA
		LFECP15/LFEC15	35	mA
		LFECP20/LFEC20	60	mA
		LFECP33/LFEC33	85	mA
I _{CCAUX}	Auxiliary Power Supply Current		15	mA
I _{CCPLL}	PLL Power Supply Current		5	mA
I _{CCIO}	Bank Power Supply Current ⁶		2	mA
I _{CCJ}	V _{CCJ} Power Supply Current		5	mA

1. For further information about supply current, please see the list of technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.

3. Frequency 0MHz.

4. Pattern represents a "blank" configuration data file.

5. T_J=25°C, power supplies at nominal voltage.

6. Per bank.

sysl/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V _{IL}		V _{IH}		V _{OL} Max. (V)	V _{OH} Min. (V)	I _{OL} ¹ (mA)	I _{OH} ¹ (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V _{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V _{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V _{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35V _{CCIO}	0.65V _{CCIO}	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35V _{CCIO}	0.65V _{CCIO}	3.6	0.4	V _{CCIO} - 0.4	8, 4	-8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.35V _{CC}	0.65V _{CC}	3.6	0.4	V _{CCIO} - 0.4	6, 2	-6, -2
					0.2	V _{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3V _{CCIO}	0.5V _{CCIO}	3.6	0.1V _{CCIO}	0.9V _{CCIO}	1.5	-0.5
SSTL3 class I	-0.3	V _{REF} - 0.2	V _{REF} + 0.2	3.6	0.7	V _{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V _{REF} - 0.2	V _{REF} + 0.2	3.6	0.5	V _{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V _{REF} - 0.18	V _{REF} + 0.18	3.6	0.54	V _{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V _{REF} - 0.18	V _{REF} + 0.18	3.6	0.35	V _{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	3.6	0.4	V _{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.6	0.4	V _{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.6	0.4	V _{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.6	0.4	V _{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.6	0.4	V _{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.6	0.4	V _{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

sysl/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold		+/-100	—	—	mV
V_{CM}	Input common mode voltage	100mV δV_{THD}	$V_{THD}/2$	1.2	1.8	V
		200mV δV_{THD}	$V_{THD}/2$	1.2	1.9	V
		350mV δV_{THD}	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	μA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100$ Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} + V_{OM})/2, R_T = 100$ Ohm	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0V$ Driver outputs shorted	—	—	6	mA

RSDS

The LatticeECP/EC devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

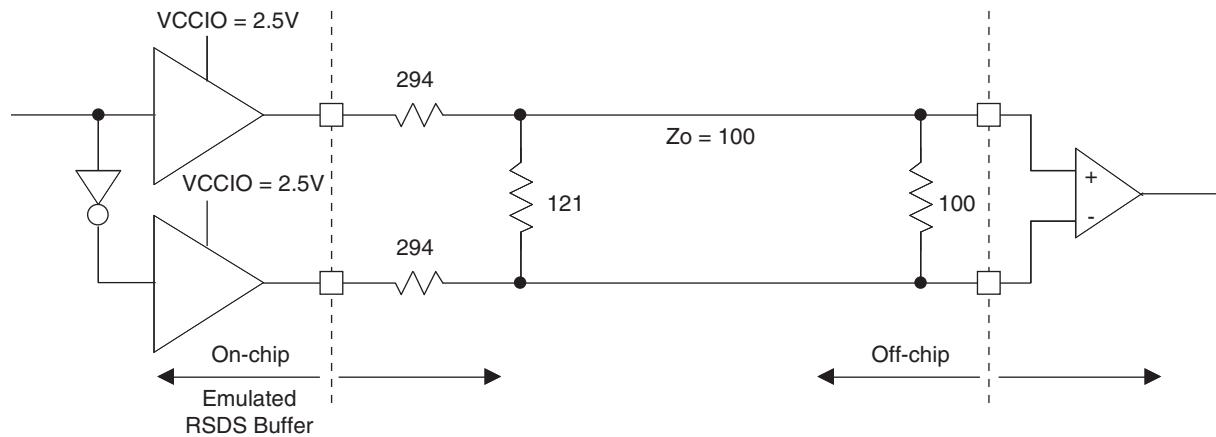
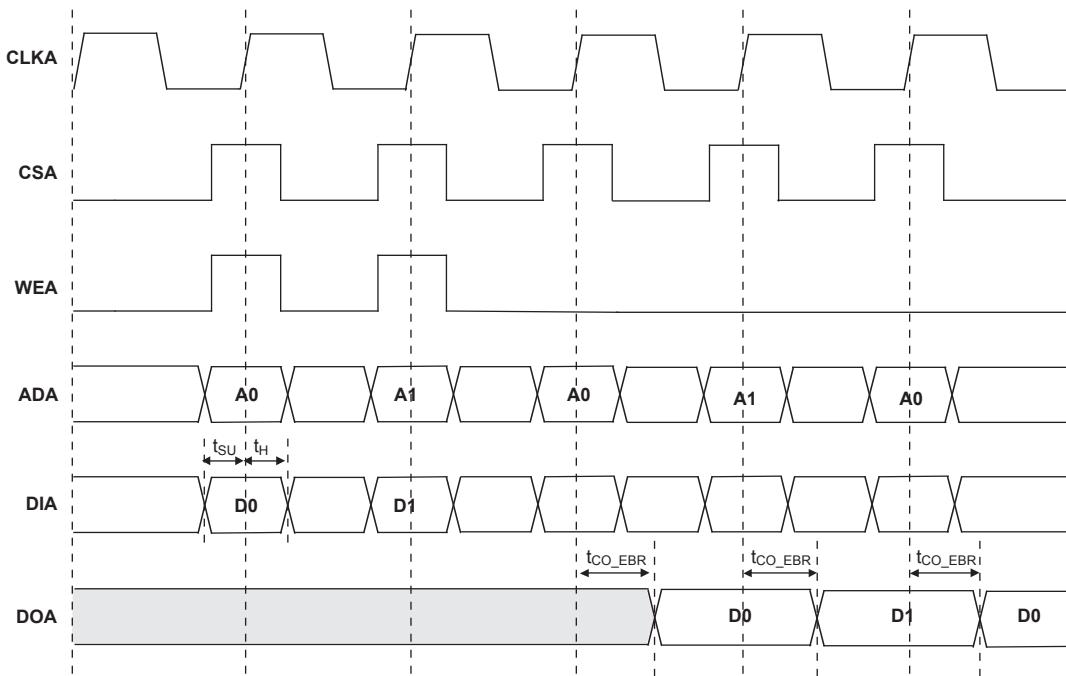


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohm
R_S	Driver series resistor	294	ohm
R_P	Driver parallel resistor	121	ohm
R_T	Receiver termination	100	ohm
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohm
I_{DC}	DC output current	3.66	mA

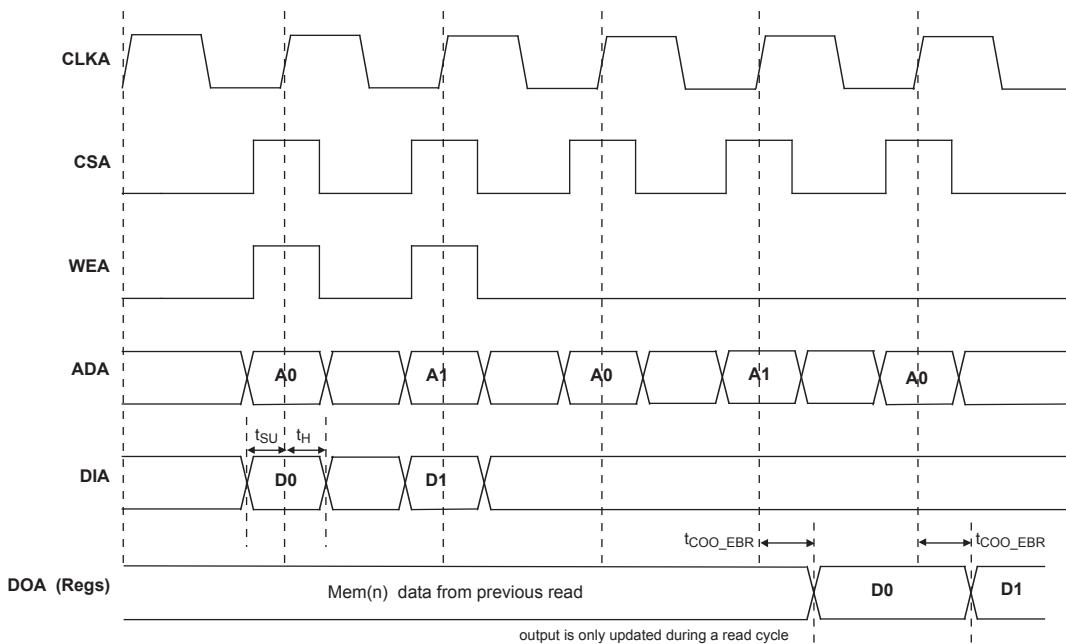
EBR Memory Timing Diagrams

Figure 3-8. Read/Write Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

Figure 3-9. Read/Write Mode with Input and Output Registers



LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
K2	PL11A	6	T	LLM0_PLLT_IN_A	PL20A	6	T	LLM0_PLLT_IN_A
K1	PL11B	6	C	LLM0_PLLC_IN_A	PL20B	6	C	LLM0_PLLC_IN_A
L2	PL12A	6	T	LLM0_PLLT_FB_A	PL21A	6	T	LLM0_PLLT_FB_A
L1	PL12B	6	C	LLM0_PLLC_FB_A	PL21B	6	C	LLM0_PLLC_FB_A
M2	PL13A	6	T		PL22A	6	T	
M1	PL13B	6	C		PL22B	6	C	
N1	PL14A	6	T		PL23A	6	T	
GND	GND6	6			GND6	6		
N2	PL14B	6	C		PL23B	6	C	
M4	PL15A	6	T	LDQS15	PL24A	6	T	LDQS24
M3	PL15B	6	C		PL24B	6	C	
P1	PL16A	6	T		PL25A	6	T	
R1	PL16B	6	C		PL25B	6	C	
P2	PL17A	6	T		PL26A	6	T	
P3	PL17B	6	C		PL26B	6	C	
N3	PL18A	6	T	VREF1_6	PL27A	6	T	VREF1_6
N4	PL18B	6	C	VREF2_6	PL27B	6	C	VREF2_6
GND	GND6	6			GND6	6		
GND	GND5	5			GND5	5		
P4	PB2A	5	T		PB2A	5	T	
N5	PB2B	5	C		PB2B	5	C	
P5	PB3A	5	T		PB3A	5	T	
P6	PB3B	5	C		PB3B	5	C	
R4	PB4A	5	T		PB4A	5	T	
R3	PB4B	5	C		PB4B	5	C	
T2	PB5A	5	T		PB5A	5	T	
T3	PB5B	5	C		PB5B	5	C	
R5	PB6A	5	T	BDQS6	PB6A	5	T	BDQS6
R6	PB6B	5	C		PB6B	5	C	
T4	PB7A	5	T		PB7A	5	T	
T5	PB7B	5	C		PB7B	5	C	
N6	PB8A	5	T		PB8A	5	T	
M6	PB8B	5	C		PB8B	5	C	
T6	PB9A	5	T		PB9A	5	T	
GND	GND5	5			GND5	5		
T7	PB9B	5	C		PB9B	5	C	
P7	PB10A	5	T		PB10A	5	T	
N7	PB10B	5	C		PB10B	5	C	
R7	PB11A	5	T		PB11A	5	T	
R8	PB11B	5	C		PB11B	5	C	
M7	PB12A	5	T		PB12A	5	T	
M8	PB12B	5	C		PB12B	5	C	
T8	PB13A	5	T		PB13A	5	T	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
V2	PL41B	6	C	LLM0_PLLC_IN_A	V2	PL53B	6	C	LLM0_PLLC_IN_A
U3	PL42A	6	T	LLM0_PLLT_FB_A	U3	PL54A	6	T	LLM0_PLLT_FB_A
V3	PL42B	6	C	LLM0_PLLC_FB_A	V3	PL54B	6	C	LLM0_PLLC_FB_A
U4	PL43A	6	T		U4	PL55A	6	T	
V5	PL43B	6	C		V5	PL55B	6	C	
W1	PL44A	6	T		W1	PL56A	6	T	
GND	GND6	6			GND	GND6	6		
W2	PL44B	6	C		W2	PL56B	6	C	
Y1	PL45A	6	T	LDQS45	Y1	PL57A	6	T	LDQS57
Y2	PL45B	6	C		Y2	PL57B	6	C	
AA1	PL46A	6	T		AA1	PL58A	6	T	
AA2	PL46B	6	C		AA2	PL58B	6	C	
W4	PL47A	6	T		W4	PL59A	6	T	
V4	PL47B	6	C		V4	PL59B	6	C	
W3	PL48A	6	T	VREF1_6	W3	PL68A	6	T	VREF1_6
Y3	PL48B	6	C	VREF2_6	Y3	PL68B	6	C	VREF2_6
GND	GND6	6			GND	GND6	6		
GND	GND5	5			GND	GND6	6		
GND	-				GND	GND6	6		
GND	-				GND	GND5	5		
GND	GND5	5			GND	GND5	5		
V7	PB10A	5	T		V7	PB10A	5	T	
T6	PB10B	5	C		T6	PB10B	5	C	
V8	PB11A	5	T		V8	PB11A	5	T	
U7	PB11B	5	C		U7	PB11B	5	C	
W5	PB12A	5	T		W5	PB12A	5	T	
U6	PB12B	5	C		U6	PB12B	5	C	
AA3	PB13A	5	T		AA3	PB13A	5	T	
GND	GND5	5			GND	GND5	5		
AB3	PB13B	5	C		AB3	PB13B	5	C	
Y6	PB14A	5	T	BDQS14	Y6	PB14A	5	T	BDQS14
V6	PB14B	5	C		V6	PB14B	5	C	
AA5	PB15A	5	T		AA5	PB15A	5	T	
W6	PB15B	5	C		W6	PB15B	5	C	
Y5	PB16A	5	T		Y5	PB16A	5	T	
Y4	PB16B	5	C		Y4	PB16B	5	C	
AA4	PB17A	5	T		AA4	PB17A	5	T	
GND	GND5	5			GND	GND5	5		
AB4	PB17B	5	C		AB4	PB17B	5	C	
Y7	PB18A	5	T		Y7	PB18A	5	T	
W8	PB18B	5	C		W8	PB18B	5	C	
W7	PB19A	5	T		W7	PB19A	5	T	
U8	PB19B	5	C		U8	PB19B	5	C	
W9	PB20A	5	T		W9	PB20A	5	T	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
N22	PR30A	3	T		N22	PR42A	3	T	
N19	PR29B	3	C		N19	PR41B	3	C	
N18	PR29A	3	T		N18	PR41A	3	T	
M21	PR28B	3	C		M21	PR40B	3	C	
L20	PR28A	3	T	RDQS28	L20	PR40A	3	T	RDQS40
L21	PR27B	3	C		L21	PR39B	3	C	
GND	GND3	3			GND	GND3	3		
M20	PR27A	3	T		M20	PR39A	3	T	
M18	PR26B	3	C		M18	PR38B	3	C	
M19	PR26A	3	T		M19	PR38A	3	T	
M22	PR25B	3	C		M22	PR37B	3	C	
L22	PR25A	3	T		L22	PR37A	3	T	
K22	PR24B	3	C		K22	PR36B	3	C	
K21	PR24A	3	T		K21	PR36A	3	T	
J22	PR22B	2	C	PCLKC2_0	J22	PR34B	2	C	PCLKC2_0
GND	GND2	2			GND	GND2	2		
J21	PR22A	2	T	PCLKT2_0	J21	PR34A	2	T	PCLKT2_0
H22	PR21B	2	C		H22	PR33B	2	C	
H21	PR21A	2	T		H21	PR33A	2	T	
L19	PR20B	2	C		L19	PR32B	2	C	
L18	PR20A	2	T		L18	PR32A	2	T	
K20	PR19B	2	C		K20	PR31B	2	C	
J20	PR19A	2	T	RDQS19	J20	PR31A	2	T	RDQS31
K19	PR18B	2	C		K19	PR30B	2	C	
GND	GND2	2			GND	GND2	2		
K18	PR18A	2	T		K18	PR30A	2	T	
G22	PR17B	2	C		G22	PR29B	2	C	
F22	PR17A	2	T		F22	PR29A	2	T	
F21	PR16B	2	C		F21	PR28B	2	C	
E22	PR16A	2	T		E22	PR28A	2	T	
E21	PR15B	2	C		E21	PR27B	2	C	
D22	PR15A	2	T		D22	PR27A	2	T	
G21	PR14B	2	C		G21	PR26B	2	C	
G20	PR14A	2	T		G20	PR26A	2	T	
GND	GND2	2			GND	GND2	2		
J18	PR13B	2	C		J18	PR25B	2	C	
H19	PR13A	2	T		H19	PR25A	2	T	
J19	PR12B	2	C		J19	PR24B	2	C	
H20	PR12A	2	T		H20	PR24A	2	T	
H17	PR11B	2	C		H17	PR23B	2	C	
H18	PR11A	2	T		H18	PR23A	2	T	RDQS23
D21	PR9B	2	C	RUM0_PLLC_FB_A	D21	PR17B	2	C	RUM0_PLLC_FB_A
GND	GND2	2			GND	GND2	2		
GND	-	-			GND	GND2	2		

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
C22	PR9A	2	T	RUM0_PLLT_FB_A	C22	PR17A	2	T	RUM0_PLLT_FB_A
G19	PR8B	2	C	RUM0_PLLC_IN_A	G19	PR16B	2	C	RUM0_PLLC_IN_A
G18	PR8A	2	T	RUM0_PLLT_IN_A	G18	PR16A	2	T	RUM0_PLLT_IN_A
F20	PR7B	2	C		F20	PR15B	2	C	
F19	PR7A	2	T		F19	PR15A	2	T	
E20	PR6B	2	C		E20	PR14B	2	C	
D20	PR6A	2	T	RDQS6	D20	PR14A	2	T	RDQS14
C21	PR5B	2	C		C21	PR13B	2	C	
GND	-	-			GND	GND2	2		
C20	PR5A	2	T		C20	PR13A	2	T	
F18	PR4B	2	C		F18	PR12B	2	C	
E18	PR4A	2	T		E18	PR12A	2	T	
B22	PR3B	2	C		B22	PR11B	2	C	
B21	PR3A	2	T		B21	PR11A	2	T	
GND	-	-			GND	GND2	2		
E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2
D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2
GND	GND2	2			GND	GND2	2		
GND	GND1	1			GND	GND1	1		
GND	-	-			GND	GND1	1		
G17	PT57B	1	C		G17	PT57B	1	C	
GND	-	-			GND	GND1	1		
F17	PT57A	1	T		F17	PT57A	1	T	
D18	PT56B	1	C		D18	PT56B	1	C	
C18	PT56A	1	T		C18	PT56A	1	T	
C19	PT55B	1	C		C19	PT55B	1	C	
B20	PT55A	1	T		B20	PT55A	1	T	
D17	PT54B	1	C		D17	PT54B	1	C	
C16	PT54A	1	T	TDQS54	C16	PT54A	1	T	TDQS54
B19	PT53B	1	C		B19	PT53B	1	C	
GND	GND1	1			GND	GND1	1		
A20	PT53A	1	T		A20	PT53A	1	T	
E17	PT52B	1	C		E17	PT52B	1	C	
C17	PT52A	1	T		C17	PT52A	1	T	
F16	PT51B	1	C		F16	PT51B	1	C	
E16	PT51A	1	T		E16	PT51A	1	T	
F15	PT50B	1	C		F15	PT50B	1	C	
D16	PT50A	1	T		D16	PT50A	1	T	
B18	PT49B	1	C		B18	PT49B	1	C	
GND	GND1	1			GND	GND1	1		
A19	PT49A	1	T		A19	PT49A	1	T	
B17	PT48B	1	C		B17	PT48B	1	C	
A18	PT48A	1	T		A18	PT48A	1	T	
B16	PT47B	1	C		B16	PT47B	1	C	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFECP20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
P5	PL32B	6	C		P5	PL44B	6	C	
P6	PL33A	6	T		P6	PL45A	6	T	
R5	PL33B	6	C		R5	PL45B	6	C	
U1	PL34A	6	T		U1	PL46A	6	T	
U2	PL34B	6	C		U2	PL46B	6	C	
T3	PL35A	6	T		T3	PL47A	6	T	
GND	GND6	6			GND	GND6	6		
T4	PL35B	6	C		T4	PL47B	6	C	
R6	PL36A	6	T	LDQS36	R6	PL48A	6	T	LDQS48
T5	PL36B	6	C		T5	PL48B	6	C	
T6	PL37A	6	T		T6	PL49A	6	T	
U5	PL37B	6	C		U5	PL49B	6	C	
U3	PL38A	6	T		U3	PL50A	6	T	
U4	PL38B	6	C		U4	PL50B	6	C	
V1	PL39A	6	T		V1	PL51A	6	T	
GND	GND6	6			GND	GND6	6		
V2	PL39B	6	C		V2	PL51B	6	C	
U7	TCK	6			U7	TCK	6		
V4	TDI	6			V4	TDI	6		
V5	TMS	6			V5	TMS	6		
V3	TDO	6			V3	TDO	6		
U6	VCCJ	6			U6	VCCJ	6		
W1	PL41A	6	T	LLM0_PLLT_IN_A	W1	PL53A	6	T	LLM0_PLLT_IN_A
W2	PL41B	6	C	LLM0_PLLC_IN_A	W2	PL53B	6	C	LLM0_PLLC_IN_A
V6	PL42A	6	T	LLM0_PLLT_FB_A	V6	PL54A	6	T	LLM0_PLLT_FB_A
W6	PL42B	6	C	LLM0_PLLC_FB_A	W6	PL54B	6	C	LLM0_PLLC_FB_A
Y1	PL43A	6	T		Y1	PL55A	6	T	
Y2	PL43B	6	C		Y2	PL55B	6	C	
W3	PL44A	6	T		W3	PL56A	6	T	
GND	GND6	6			GND	GND6	6		
W4	PL44B	6	C		W4	PL56B	6	C	
AA1	PL45A	6	T	LDQS45	AA1	PL57A	6	T	LDQS57
AB1	PL45B	6	C		AB1	PL57B	6	C	
Y4	PL46A	6	T		Y4	PL58A	6	T	
Y3	PL46B	6	C		Y3	PL58B	6	C	
AC1	PL47A	6	T		AC1	PL59A	6	T	
AB2	PL47B	6	C		AB2	PL59B	6	C	
AA2	NC	-			AA2	PL60A	6	T	
-	-	-			GND	GND6	6		
AA3	NC	-			AA3	PL60B	6	C	
W5	NC	-			W5	PL61A	6	T	
Y5	NC	-			Y5	PL61B	6	C	

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeECP Commercial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP6E-3F484C	224	-3	fpBGA	484	COM	6.1K
LFECP6E-4F484C	224	-4	fpBGA	484	COM	6.1K
LFECP6E-5F484C	224	-5	fpBGA	484	COM	6.1K
LFECP6E-3F256C	195	-3	fpBGA	256	COM	6.1K
LFECP6E-4F256C	195	-4	fpBGA	256	COM	6.1K
LFECP6E-5F256C	195	-5	fpBGA	256	COM	6.1K
LFECP6E-3Q208C	147	-3	PQFP	208	COM	6.1K
LFECP6E-4Q208C	147	-4	PQFP	208	COM	6.1K
LFECP6E-5Q208C	147	-5	PQFP	208	COM	6.1K
LFECP6E-3T144C	97	-3	TQFP	144	COM	6.1K
LFECP6E-4T144C	97	-4	TQFP	144	COM	6.1K
LFECP6E-5T144C	97	-5	TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP10E-3F484C	288	-3	fpBGA	484	COM	10.2K
LFECP10E-4F484C	288	-4	fpBGA	484	COM	10.2K
LFECP10E-5F484C	288	-5	fpBGA	484	COM	10.2K
LFECP10E-3F256C	195	-3	fpBGA	256	COM	10.2K
LFECP10E-4F256C	195	-4	fpBGA	256	COM	10.2K
LFECP10E-5F256C	195	-5	fpBGA	256	COM	10.2K
LFECP10E-3Q208C	147	-3	PQFP	208	COM	10.2K
LFECP10E-4Q208C	147	-4	PQFP	208	COM	10.2K
LFECP10E-5Q208C	147	-5	PQFP	208	COM	10.2K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP15E-3F484C	352	-3	fpBGA	484	COM	15.3K
LFECP15E-4F484C	352	-4	fpBGA	484	COM	15.3K
LFECP15E-5F484C	352	-5	fpBGA	484	COM	15.3K
LFECP15E-3F256C	195	-3	fpBGA	256	COM	15.3K
LFECP15E-4F256C	195	-4	fpBGA	256	COM	15.3K
LFECP15E-5F256C	195	-5	fpBGA	256	COM	15.3K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP20E-3F672C	400	-3	fpBGA	672	COM	19.7K
LFECP20E-4F672C	400	-4	fpBGA	672	COM	19.7K
LFECP20E-5F672C	400	-5	fpBGA	672	COM	19.7K
LFECP20E-3F484C	360	-3	fpBGA	484	COM	19.7K
LFECP20E-4F484C	360	-4	fpBGA	484	COM	19.7K
LFECP20E-5F484C	360	-5	fpBGA	484	COM	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP33E-3F672C	496	-3	fpBGA	672	COM	32.8K
LFECP33E-4F672C	496	-4	fpBGA	672	COM	32.8K
LFECP33E-5F672C	496	-5	fpBGA	672	COM	32.8K

LatticeECP Commercial (Continued)

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP33E-3F484C	360	-3	fpBGA	484	COM	32.8K
LFECP33E-4F484C	360	-4	fpBGA	484	COM	32.8K
LFECP33E-5F484C	360	-5	fpBGA	484	COM	32.8K

LatticeEC Industrial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC1E-3Q208I	112	-3	PQFP	208	IND	1.5K
LFEC1E-4Q208I	112	-4	PQFP	208	IND	1.5K
LFEC1E-3T144I	97	-3	TQFP	144	IND	1.5K
LFEC1E-4T144I	97	-4	TQFP	144	IND	1.5K
LFEC1E-3T100I	67	-3	TQFP	100	IND	1.5K
LFEC1E-4T100I	67	-4	TQFP	100	IND	1.5K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC3E-3F256I	160	-3	fpBGA	256	IND	3.1K
LFEC3E-4F256I	160	-4	fpBGA	256	IND	3.1K
LFEC3E-3Q208I	145	-3	PQFP	208	IND	3.1K
LFEC3E-4Q208I	145	-4	PQFP	208	IND	3.1K
LFEC3E-3T144I	97	-3	TQFP	144	IND	3.1K
LFEC3E-4T144I	97	-4	TQFP	144	IND	3.1K
LFEC3E-3T100I	67	-3	TQFP	100	IND	3.1K
LFEC3E-4T100I	67	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC6E-3F484I	224	-3	fpBGA	484	IND	6.1K
LFEC6E-4F484I	224	-4	fpBGA	484	IND	6.1K
LFEC6E-3F256I	195	-3	fpBGA	256	IND	6.1K
LFEC6E-4F256I	195	-4	fpBGA	256	IND	6.1K
LFEC6E-3Q208I	147	-3	PQFP	208	IND	6.1K
LFEC6E-4Q208I	147	-4	PQFP	208	IND	6.1K
LFEC6E-3T144I	97	-3	TQFP	144	IND	6.1K
LFEC6E-4T144I	97	-4	TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC10E-3F484I	288	-3	fpBGA	484	IND	10.2K
LFEC10E-4F484I	288	-4	fpBGA	484	IND	10.2K
LFEC10E-3F256I	195	-3	fpBGA	256	IND	10.2K
LFEC10E-4F256I	195	-4	fpBGA	256	IND	10.2K
LFEC10E-3 P208I	147	-3	PQFP	208	IND	10.2K
LFEC10E-4 P208I	147	-4	PQFP	208	IND	10.2K

LatticeECP Industrial (Continued)

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP20E-3F672I	400	-3	fpBGA	672	IND	19.7K
LFECP20E-4F672I	400	-4	fpBGA	672	IND	19.7K
LFECP20E-3F484I	360	-3	fpBGA	484	IND	19.7K
LFECP20E-4F484I	360	-4	fpBGA	484	IND	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP33E-3F672I	496	-3	fpBGA	672	IND	32.8K
LFECP33E-4F672I	496	-4	fpBGA	672	IND	32.8K
LFECP33E-3F484I	360	-3	fpBGA	484	IND	32.8K
LFECP33E-4F484I	360	-4	fpBGA	484	IND	32.8K

LatticeECP Commercial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN484C	360	-3	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-4FN484C	360	-4	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-5FN484C	360	-5	Lead-Free fpBGA	484	COM	32.8K

LatticeEC Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC1E-3QN208I	112	-3	Lead-Free PQFP	208	IND	1.5K
LFEC1E-4QN208I	112	-4	Lead-Free PQFP	208	IND	1.5K
LFEC1E-3TN144I	97	-3	Lead-Free TQFP	144	IND	1.5K
LFEC1E-4TN144I	97	-4	Lead-Free TQFP	144	IND	1.5K
LFEC1E-3TN100I	67	-3	Lead-Free TQFP	100	IND	1.5K
LFEC1E-4TN100I	67	-4	Lead-Free TQFP	100	IND	1.5K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC3E-3FN256I	160	-3	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-4FN256I	160	-4	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-3QN208I	145	-3	Lead-Free PQFP	208	IND	3.1K
LFEC3E-4QN208I	145	-4	Lead-Free PQFP	208	IND	3.1K
LFEC3E-3TN144I	97	-3	Lead-Free TQFP	144	IND	3.1K
LFEC3E-4TN144I	97	-4	Lead-Free TQFP	144	IND	3.1K
LFEC3E-3TN100I	67	-3	Lead-Free TQFP	100	IND	3.1K
LFEC3E-4TN100I	67	-4	Lead-Free TQFP	100	IND	3.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFEC6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFEC6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFEC6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFEC10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K



LatticeECP/EC Family Data Sheet

Supplemental Information

September 2012

Data Sheet

For Further Information

A variety of technical notes for the LatticeECP/EC family are available on the Lattice web site at www.latticesemi.com.

- LatticeECP/EC sysIO Usage Guide (TN1056)
- LatticeECP/EC sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC Devices (TN1051)
- LatticeECP/EC DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeECP-DSP sysDSP Usage Guide (TN1057)
- LatticeECP/EC sysCONFIG Usage Guide (TN1053)
- IEEE 1149.1 Boundary Scan Testability in Lattice Devices

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTI, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com